



Materials Declaration Form


IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

* : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	25-08-2017
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement	
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Legal Statement	
Supplier Acceptance *	true
	Legal Declaration *
	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM8S207RBT6C STM8S207RBT6CTR	U01R*765XXXV	A	959	25-08-2017
	Amount	UoM	Unit type	ST ECOPACK Grade
	645.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	14x14x1.4	64	L Bend	
Comment	Package : 1R LQFP 64 14x14x1.4 1 0087217			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	U01R*765XXXV				6000001.0	999999.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	6.698	mg	supplier	die	Silicon (Si)	7440-21-3		6.492	mg	969245	10065
				supplier	metallization	Aluminium (Al)	7429-90-5		0.018	mg	2687	28
				supplier	metallization	Copper (Cu)	7440-50-8		0.060	mg	8958	93
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.007	mg	1045	11
				supplier	metallization	Titanium (Ti)	7440-32-6		0.009	mg	1344	14
				supplier	Passivation	Silicon Nitride	12033-89-5		0.016	mg	2389	25
				supplier	Passivation	Silicon Oxide	7631-86-9		0.096	mg	14333	149
Lead-frame	M-011 Other inorganic materials	165.354	mg	supplier	alloy	Copper (Cu)	7440-50-8		158.140	mg	956376	245179
				supplier	alloy	Nickel (Ni)	7440-02-0		4.932	mg	29825	7646
				supplier	alloy	Silicium (Si)	7440-21-3		1.069	mg	6462	1657
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.247	mg	1491	382
				supplier	coating	Nickel (Ni)	7440-02-0		0.886	mg	5360	1374
				supplier	coating	Palladium (Pd)	7440-05-3		0.057	mg	343	88
				supplier	coating	Gold (Au)	7440-57-5		0.024	mg	143	37
Die Attach	M-011 Other inorganic materials	3.617	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		2.848	mg	787500	4416
				supplier	glue or soft solder	Urethane acrylate oligomer	Proprietary		0.253	mg	70000	392
				supplier	glue or soft solder	Méthacrylate	Proprietary		0.253	mg	70000	392
				supplier	glue or soft solder	Acrylate	Proprietary		0.253	mg	70000	392
Wires	M-011 Other inorganic materials	2.157	mg	supplier	glue or soft solder	NMP	872-50-4		0.009	mg	2500	14
				supplier	Bonding wire	Gold (Au)	7440-57-5		2.157	mg	1000000	3343
Encapsulation	M-011 Other inorganic materials	467.165	mg	supplier	Moulding Compound	Solid Epoxy Resin	Proprietary		31.963	mg	68420	49555
				supplier	Moulding Compound	Phenol Resin	Proprietary		22.831	mg	48871	35397
				supplier	Moulding Compound	Silica, vitreous	60676-86-0		405.522	mg	868048	628716
				supplier	Moulding Compound	Carbon-black	1333-86-4		2.283	mg	4887	3540
Finishing	M-011 Other inorganic materials	0.010	mg	supplier	Moulding Compound	Bismuth	7440-69-9		4.566	mg	9774	7079
				supplier	connections coating	Nickel (Ni)	7440-02-0		0.009	mg	916800	14
				supplier	connections coating	Palladium (Pd)	7440-05-3		0.001	mg	58700	1
				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	24500	0